

Most Frequently Occurring Classifications of Patents Returned  
From A Search of 10/600,568 on December 23, 2003

Combined Classifications

6 257/E21.576  
5 257/723  
5 257/763  
4 257/700  
4 257/E21.582  
4 257/E23.173  
4 257/E23.193  
3 257/686  
3 257/704  
3 257/751  
3 257/758  
3 257/765  
3 257/E21.648  
3 361/760  
3 438/622  
2 174/52.4  
2 257/198  
2 257/306  
2 257/668  
2 257/685  
2 257/697  
2 257/712  
2 257/713  
2 257/717  
2 257/722  
2 257/724  
2 257/762  
2 257/764  
2 257/766  
2 257/777  
2 257/E21.278  
2 257/E21.387  
2 257/E21.507  
2 257/E21.579  
2 257/E21.645  
2 257/E21.705  
2 257/E23.094  
2 257/E23.167  
2 257/E23.19  
2 257/E25.013  
2 257/E27.012  
2 257/E29.189

2 361/749  
2 361/767  
2 361/783  
2 361/807  
2 361/810  
2 361/816  
2 361/818  
2 385/92  
2 438/109  
2 438/613  
2 438/638  
2 438/687  
2 438/724  
2 438/745

- 5 257/723 (0 OR, 5 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/688 .With large area flexible electrodes in press  
contact with opposite sides of active semiconductor chip  
and surrounded by an insulating element, e.g., ring  
257/723 .For plural devices
- 5 257/763 (0 OR, 5 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD  
257/741 .Of specified material other than unalloyed  
aluminum  
257/750 ..Layered  
257/763 ...At least one layer of molybdenum, titanium,  
or tungsten
- 4 257/700 (0 OR, 4 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/688 .With large area flexible electrodes in press  
contact with opposite sides of active semiconductor chip  
and surrounded by an insulating element, e.g., ring  
257/690 .With contact or lead  
257/700 ..Multiple contact layers separated from each  
other by insulator means and forming part of a package or  
housing (e.g., plural ceramic layer package)
- 3 257/686 (2 OR, 1 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/678 HOUSING OR PACKAGE  
257/685 .Multiple housings  
257/686 ..Stacked arrangement
- 3 257/704 (1 OR, 2 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/688 .With large area flexible electrodes in press  
contact with opposite sides of active semiconductor chip  
and surrounded by an insulating element, e.g., ring  
257/701 .Insulating material  
257/704 ..Cap or lid
- 3 257/751 (2 OR, 1 XR)  
Class 257 : ACTIVE SOLID-STATE DEVICES  
257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD  
257/741 .Of specified material other than unalloyed  
aluminum  
257/750 ..Layered

257/751 ...At least one layer forms a diffusion barrier

3 257/758 (1 OR, 2 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD

257/741 .Of specified material other than unalloyed  
aluminum

257/750 ..Layered

257/758 ...Multiple metal levels on semiconductor,  
separated by insulating layer (e.g., multiple level  
metallization for integrated circuit)

3 257/765 (0 OR, 3 XR)

Class 257 : ACTIVE SOLID-STATE DEVICES

257/734 COMBINED WITH ELECTRICAL CONTACT OR LEAD

257/741 .Of specified material other than unalloyed  
aluminum

257/750 ..Layered

257/765 ...At least one layer of an alloy containing  
aluminum

3 438/622 (1 OR, 2 XR)

Class 438 : SEMICONDUCTOR DEVICE MANUFACTURING:  
PROCESS

438/584 COATING WITH ELECTRICALLY OR THERMALLY  
CONDUCTIVE MATERIAL

438/597 .To form ohmic contact to semiconductive  
material

438/618 ..Contacting multiple semiconductive regions  
(i.e., interconnects)

438/622 ...Multiple metal levels, separated by  
insulating layer (i.e., multiple level metallization)

PLUS Search Results for S/N 10/600,568, Searched December 23, 2003 (TOP 50)

6611060	6140208	5466634	4943470	5670801
5412748	6162740	5517057	4965660	5683940
5559918	6166425	5654567	5188280	5700720
5387815	6251786	5898221	5333505	5818699
5426319	6294422	5705847	5399527	5916733
5525548	6300242	4251852	5506451	5949654
5691222	6333248	4322279	5506755	5949097
5872060	6333547	4490706	5519254	5981000
6025623	6376353	4764804	5532906	6037247
6124553	6376386	4769690	5656856	6096630